

PSE Technology Corporation

SPECIFICATION FOR APPROVAL

CUSTOMER	_____
NOMINAL FREQUENCY	8.000000 MHz
PRODUCT TYPE	TYPE F9 5x3.2 GLASS SEALED CRYSTAL
PART NUMBER	F90800021
CUSTOMER P/N	_____
ISSUE DATE	May 16, 2013
VERSION	B

APPROVED	PREPARED	QA
<i>Brenda</i>	<i>Nikhi Lu</i>	<i>Bedoya</i>
APPROVED BY CUSTOMER		
Please return one copy with approval to PSE-TW		

PSE Technology Corporation

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- *RoHS Exemption
- *HF-Halogen Free
- *REACH Compliant

A Company of PERICOM Semiconductor Corporation

TYPE F9 5x3.2 GLASS SEALED CRYSTAL

F90800021

VER.B 16-MAY-13

VERSION HISTORY

Version No.	Version Date	Customer Receipt Date	Supplier Receipt Date	Description	Notes
A	Jan. 6, 2012			Initial Release	
B	May. 16, 2013			Updated mechanical drawing	

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ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	8.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	18	pF	
Calibration Tolerance	FL	± 20	ppm	at 25°C±3°C
Operating Temperature Range	TR	-40 to +85	°C	
Frequency Stability(Frequency Deviation over the Operating Temperature Range)	F/T	± 30	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	100	Ω	Max.
Shunt Capacitance	C0	5	pF	Max.
Aging at 25°C		± 5	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	MΩ	Min

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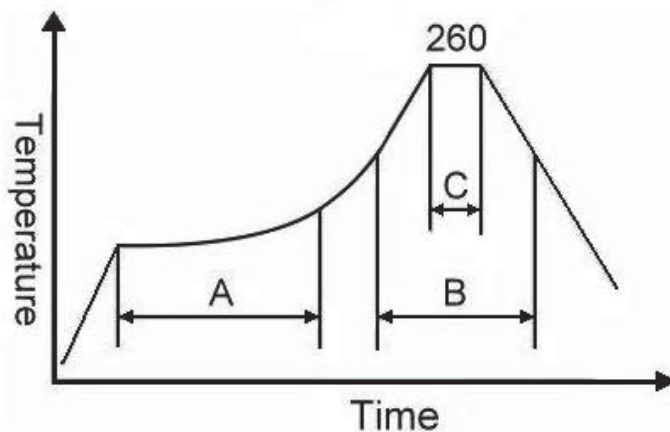
RELIABILITY SPECIFICATIONS

MECHANICAL AND ENVIRONMENTAL RATINGS:

- a) FINE LEAK TEST: JESD22-A109 (Condition 1A)
- b) GROSS LEAK TEST: JESD22-A109 (Condition C)
- c) MOISTURE RESISTANCE: JESD22-A113
- d) SHOCK: JESD22-B104 (Condition B)
- e) SOLDERABILITY : (RoHS version): J-STD-002
- f) VIBRATION: JESD22-B103
- g) SOLVENT RESISTANCE: JESD22-B107
- h) RESISTANCE TO SOLDERING HEAT (RoHS version): J-STD-020D Table 5.2 Pb free devices (3 cycles max)

SUGGESTED IR REFLOW PROFILE

*As per IPC-JEDEC J-STD-020D



Note:

	Stage	Temperature	Time
A	Preheat	150~200°C	60~120 Sec
B	Primary Heat	217°C	60~150 Sec
C	Peak	260°C	10 Sec

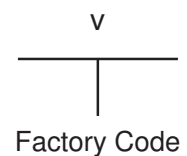
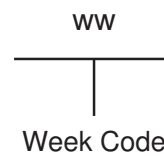
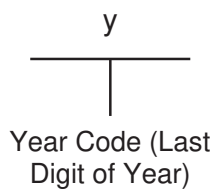
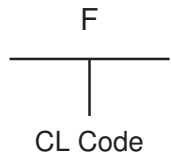
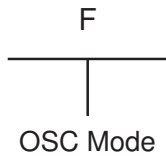
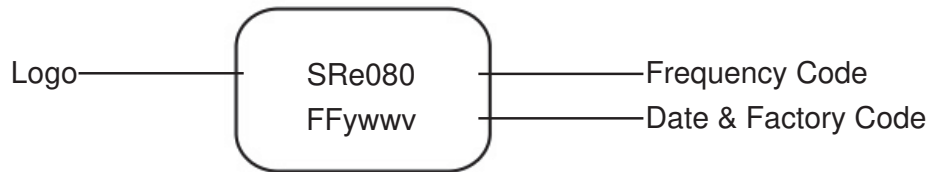
For soldering reflow profile and reliability test ratings go to: <http://www.pericom.com/pdf/sre/reflow.pdf>

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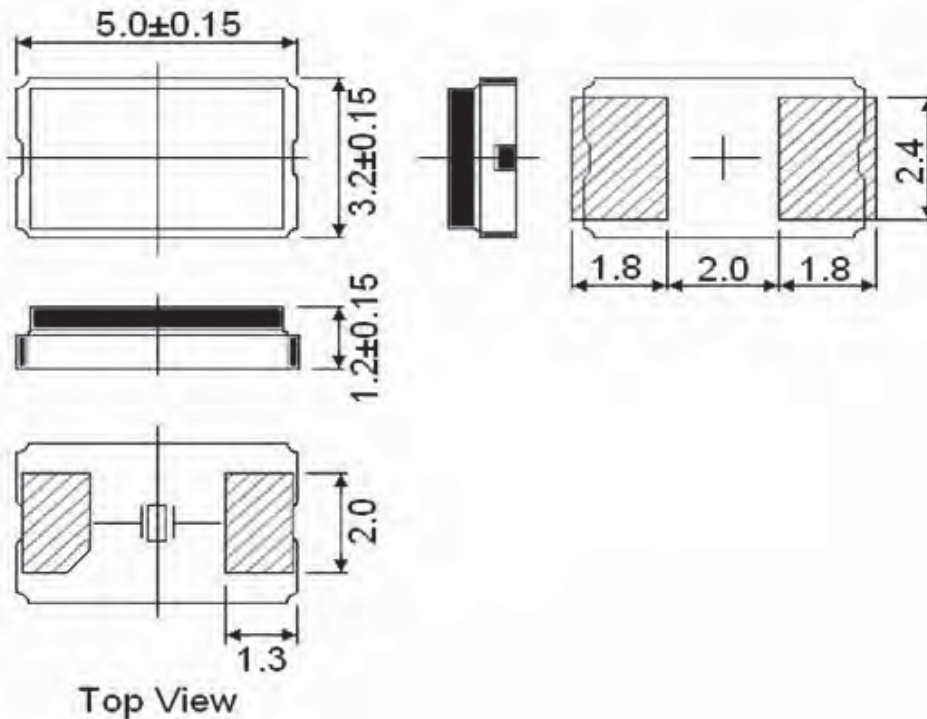
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MARKING



MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)



Note:

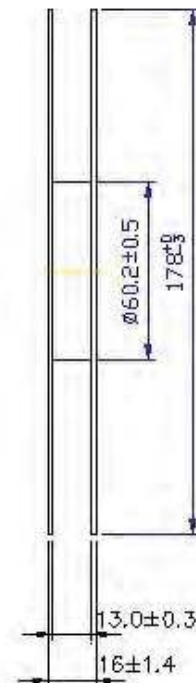
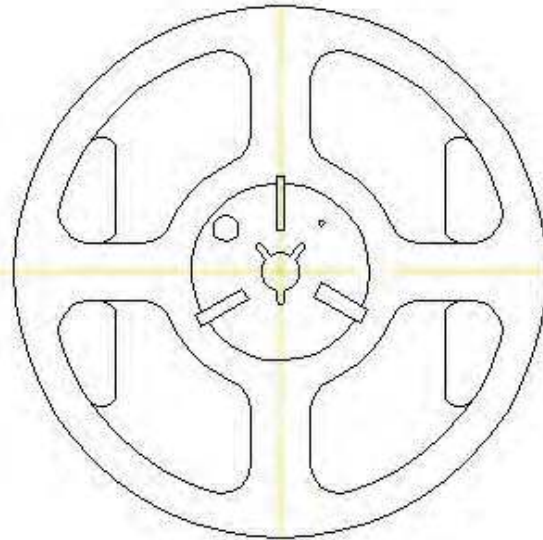
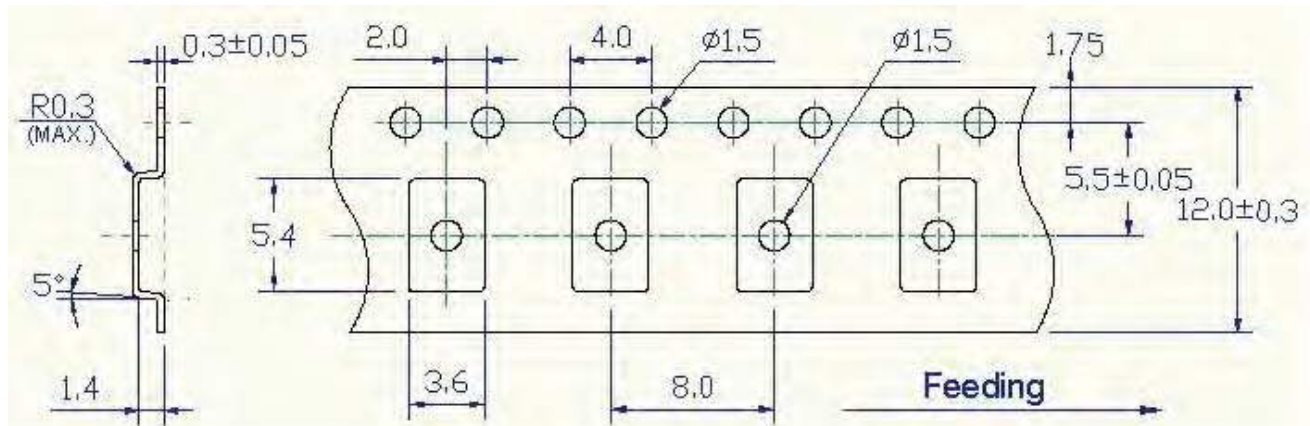
Pin shape is only for reference, and the Pin with chamfer or without chamfer is based on the real product.

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Tape & Reel



1. 230mm minimum leader which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

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PACKING

